Surface Mount Schottky Barrier Rectifier
Reverse Voltage - 20 to 200 V
Forward Current - 3.0A

FEATURES

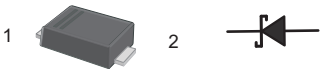
- Metal silicon junction, majority carrier conduction
- For surface mounted applications
- Low power loss, high efficiency
- High forward surge current capability
- For use in low voltage, high frequency inverters, free wheeling, and polarity protection applications

MECHANICAL DATA

- Case: SOD-123FL
- Terminals: Solderable per MIL-STD-750, Method 2026
- Approx. Weight:15mg 0.00048oz

PINNING

PIN	DESCRIPTION
1	Cathode
2	Anode



Top View
Marking Code: DS32W ---K32
DS34W ---K34
DS36W ---K36
DS38W ---K38
DS310W ---K310
DS312W ---K312
DS315W ---K315
DS320W ---K320
Simplified outline SOD-123FL and symbol

Absolute Maximum Ratings and Electrical characteristics

Ratings at 25 °C ambient temperature unless otherwise specified.Single phase, half wave, 60Hz resistive or inductive load, for capacitive load, derate by 20 %

Parameter	Symbols	DS32W	DS34W	DS36W	DS38W	DS310W	DS312W	DS315W	DS320W	Units
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	20	40	60	80	100	120	150	200	V
Maximum RMS voltage	V_{RMS}	14	28	42	56	70	84	105	140	V
Maximum DC Blocking Voltage	V_{DC}	20	40	60	80	100	120	150	200	V
Maximum Average Forward Rectified Current	$I_{F(AV)}$	3.0								A
Peak Forward Surge Current,8.3ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method)	I_{FSM}	80								A
Max Instantaneous Forward Voltage at 3 A	V_F	0.55		0.70		0.85		0.95		V
Maximum DC Reverse Current T_a = 25°C at Rated DC Reverse Voltage T_a =100°C	I_R	0.5 10		0.3 5						mA
Typical Junction Capacitance (1)	C_j	250		160						pF
Typical Thermal Resistance (2)	$R_{\theta JA}$	80								°C/W
Operating Junction Temperature Range	T_j	-55 ~ +150								°C
Storage Temperature Range	T_{stg}	-55 ~ +150								°C

(1) Measured at 1 MHz and applied reverse voltage of 4 V D.C
(2) P.C.B. mounted with 2.0" X 2.0" (5 X 5 cm) copper pad areas.

Fig.1 Forward Current Derating Curve

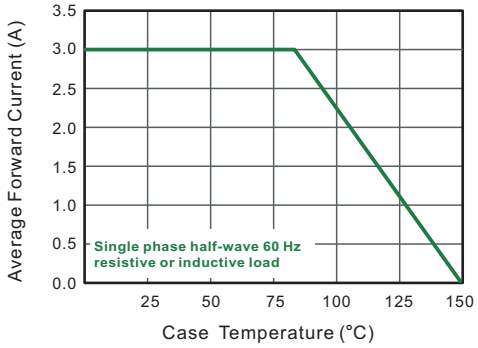


Fig.2 Typical Reverse Characteristics

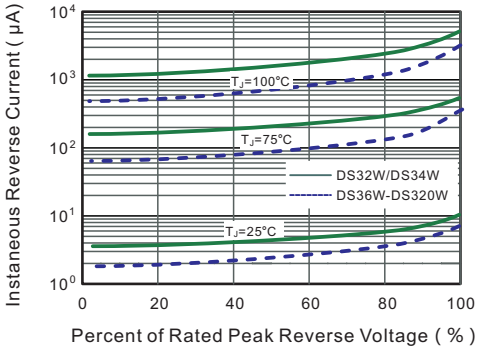


Fig.3 Typical Forward Characteristic

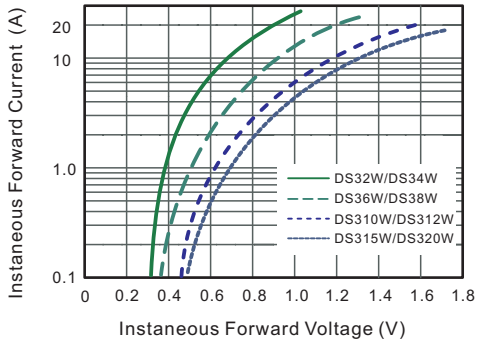


Fig.4 Typical Junction Capacitance

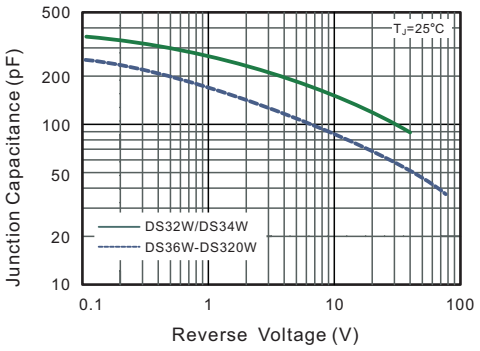


Fig.5 Maximum Non-Repetitive Peak Forward Surage Current

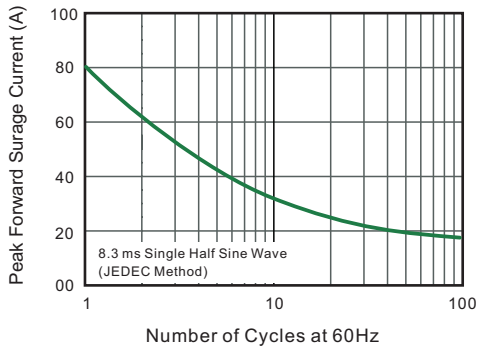
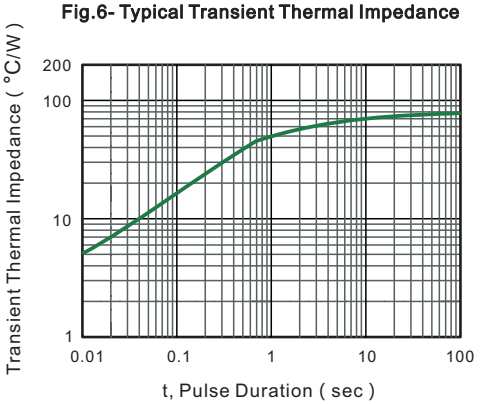
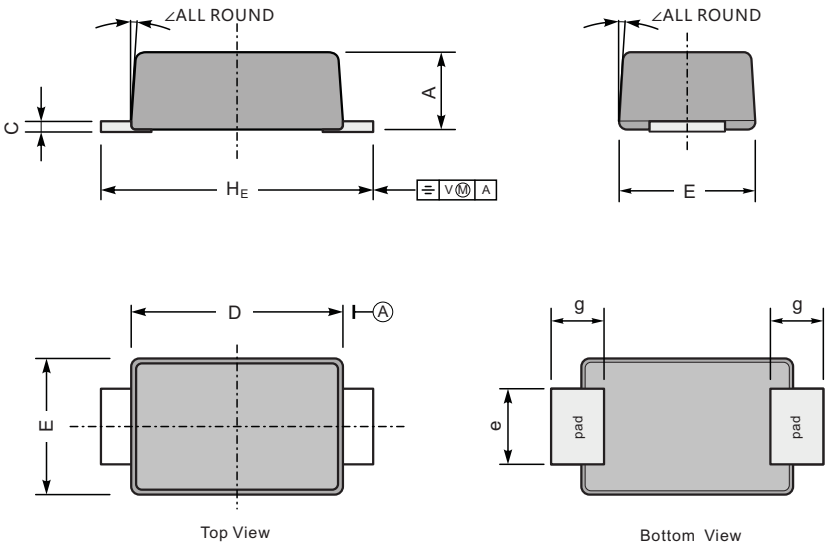


Fig.6- Typical Transient Thermal Impedance



PACKAGE OUTLINE

Plastic surface mounted package; 2 leads



UNIT		A	C	D	E	e	g	H_E	∠
mm	max	1.1	0.20	2.9	1.9	1.1	0.9	3.8	7°
	min	0.9	0.12	2.6	1.7	0.8	0.7	3.5	
mil	max	43	7.9	114	75	43	35	150	
	min	35	4.7	102	67	31	28	138	

The recommended mounting pad size

